

Title (en)

Assembly with a power semiconductor module and a connector

Title (de)

Anordnung mit Leistungshalbleitermodul und mit Anschlussverbinder

Title (fr)

Assemblage avec un module semiconducteur de puissance et un connecteur

Publication

EP 1758214 B1 20071219 (DE)

Application

EP 06017500 A 20060823

Priority

DE 102005039946 A 20050824

Abstract (en)

[origin: EP1758214A1] The arrangement includes a power semiconductor module that has a housing (3), and connectors (6) for load connection and auxiliary connections. Spring contact components are arranged projecting from the housing. The housing is also provided with first connecting units for coupling with the connectors, and second connecting units (62,64) and metal molded portion (7) with contact areas for coming in contact with the spring contact components. The metal molded portion also has contact sections (70) for external connection of the power semiconductor module.

IPC 8 full level

H01R 31/06 (2006.01)

CPC (source: EP)

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